

TENTATIVE OUTLINE

Special Thematic Issue for CURRENT CHINESE COMPUTER SCIENCE

Special Issue Topic: Data Engineering & Machine Learning Applications

Guest Editors

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AIMS & SCOPE

In the evolution of contemporary computing, data science and data engineering played an indispensable role towards automation of data driven systems ranging from applications involving business process to internet of things. This involves addressing new approaches and methods for handling and mining complex data volumes. Research in data science, data mining, and machine learning refers to designing, developing, and analyzing new ways for discovery of complex and interesting data patterns such as seasonal, emerging and diminishing from the underlying data with complex structure. Some of these data forms include sequence/time series data; temporal/spatio-temporal data; XML/Web data; time stamped temporal data; sensor data. All such forms of data pose a serious challenge to data mining research community and implicitly throw an immediate need to come up with new ideas, methods, methodologies, algorithms, frameworks for storing, managing, analyzing data which facilitates discovering hidden patterns and trends underlying structured/unstructured data which may exist in several complex forms.

This special issue aims at essentially focusing on the recent advances and developments for complex data analysis such as sensor, temporal, medical, stream, event, weblog, to social network data. We welcome research contributions and submissions which pave the way for foundation of new algorithms, methods and data representations for pattern discovery from machine learning, statistical and deep learning areas. To summarize, the objective of this special issue on “Data Engineering & Machine Learning Applications” is to create a knowledge sharing forum for researchers from both industry and academia to contribute, and share their real time, practical and development experiences and original results from all Data and Knowledge Discovery (KDD) areas which includes but not limited to Data Mining, Temporal and Spatial Data Mining, Machine Learning, Knowledge Engineering, Data Visualization, Decision Making and Support Systems, and all other emerging applications. The special issue solicits

contributions of researchers from both academia and industry but not limited to the following topical areas

- ❖ Novel approaches for Temporal / Spatial/Spatio-Temporal Association analysis
- ❖ Pattern discovery from Time stamped Temporal and Interval databases
- ❖ Novel models and algorithms for handling high dimensional data
- ❖ Data Stream Mining and Video Content Analysis
- ❖ Novel approaches for handling Uncertain and Imbalanced data
- ❖ Supervised / Un-supervised techniques for mining healthcare data
- ❖ Deep learning and Big data applications
- ❖ Periodic / Sequential pattern mining
- ❖ Evolutionary algorithms
- ❖ Time series similarity and Irregular temporal data analysis
- ❖ Mining Text , Web and Social network data
- ❖ Data and Image Fusion applications
- ❖ Applications of Data Mining in Anomaly and Intrusion detection
- ❖ Applications to medical informatics

Submission Guidelines

Papers submitted for publication to this special issue will be peer reviewed and selected on basis of their quality and relevance to the theme of this special issue. Submitted manuscripts should not have been published previously, nor be under consideration for publication elsewhere. Manuscripts may be directly to the submission site <https://bentham.manuscriptpoint.com/journals/cccs>. Any queries therein should be addressed to info@benthamsience.net

Proposed Schedule:

- Manuscript Submission Deadline: May 15th , 2020
- Peer Review Due: July 1st , 2020
- Revision Due: August 1st , 2020
- Announcement of Acceptance by Guest Editor: Aug 15th , 2020
- Final Manuscript Due: Aug 30th , 2020